External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00084	5.0	0.01618
	Lead alloy	Silver (Ag)	7440-22-4	0.00042	2.5	0.00809
	Lead alloy	Lead (Pb)	7439-92-1	0.01557	92.5	0.29938
			Subtotal	0.01683	100	0.32365
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.23927	100.0	4.6
			Subtotal	0.23927	100	4.6
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.22887	100.0	4.4
			Subtotal	0.22887	100	4.4
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.4044	100.0	27
			Subtotal	1.4044	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02754	0.04	0.52948
	Copper alloy	Iron (Fe)	7439-89-6	0.06885	0.1	1.3237
	Copper alloy	Copper (Cu)	7440-50-8	68.75582	99.86	1,321.84682
			Subtotal	68.85221	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.54548	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.68135	16.0	90
	Filler	Silica fused	60676-86-0	21.94381	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.08778	0.3	1.6875
			Subtotal	29.25842	100	562.5
			Total	100	100	NaN

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